SCAS015B - JUNE 1987 - REVISED APRIL 1996

•	Eight Latches in a Single Package 3-State Bus Driving True Outputs	DB, DW, OR NT PACKAG (TOP VIEW)		
•	Full Parallel Access for Loading	1Q 🕇		
٠	Buffered Input and Output-Enable Pins	5	2	24 0 0 1 23 0 1D
•	Inputs Are TTL-Voltage Compatible	3Q [3	22 2 2D
•	Flow-Through Architecture Optimizes	4Q [4	21] 3D
	PCB Layout	GND [5	20 🛛 4D
•	Center-Pin V _{CC} and GND Configurations	- 4	6	19 V _{CC}
•	Minimize High-Speed Switching Noise	GND [7	18 VCC
•		GND [8	17 🛛 5D
•	EPIC [™] (Enhanced-Performance Implanted	5Q [9	16 🛛 6D
	CMOS) 1-µm Process	6Q [10	15 🛛 7D
•	500-mA Typical Latch-Up Immunity at	7Q 🛛	11	14 🛛 8D
	125°C	8Q [12	13] LE
٠	Package Options Include Plastic Small-Outline (DW) and Shrink	l]

Small-Outline (DW) and Shrink Small-Outline (DB) Packages, and Standard Plastic 300-mil DIPs (NT)

description

This 8-bit latch features 3-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the 74ACT11373 are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When the enable is taken low, the Q outputs are latched at the levels that were set up at the D inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impendance third state and increased drive provide the capability to drive the bus lines in a bus-organized system without need for interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are off.

The 74ACT11373 is characterized for operation from -40°C to 85°C.

(each latch)									
	INPUTS		OUTPUT						
OE	LE	D	Q						
L	Н	Н	Н						
L	н	L	L						
L	L	Х	Q ₀						
н	Х	Х	z						

ELINCTION TABLE



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74ACT11373 OCTAL TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS SCAS015B – JUNE 1987 – REVISED APRIL 1996

logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





SCAS015B - JUNE 1987 - REVISED APRIL 1996

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

	5 V 5 V nA nA nA
Continuous current through V_{CC} or GND $\pm 200 \text{ m/s}$ Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2): DB package 0.65 W DW package 1.7 W NT package 1.3 W	W W W
Storage temperature range, T _{stg} –65°C to 150°C	°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the NT package, which has a trace length of zero.

recommended operating conditions

		MIN	MAX	UNIT
VCC	Supply voltage	4.5	5.5	V
VIH	High-level input voltage	2		V
VIL	Low-level input voltage		0.8	V
VI	Input voltage	0	VCC	V
VO	Output voltage	0	VCC	V
ЮН	High-level output current		-24	mA
IOL	Low-level output current		24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0	10	ns/V
Т _А	Operating free-air temperature	-40	85	°C



SCAS015B - JUNE 1987 - REVISED APRIL 1996

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	vcc	T _A = 25°C		MIN	MAY	UNIT	
PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	WIIN	MAX	UNIT
	L 50 A		4.4			4.4		
	I _{OH} = -50 μA	5.5 V	5.4			5.4		
VOH		4.5 V	3.94			3.8		V
	$I_{OH} = -24 \text{ mA}$		4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
	I _{OL} = 50 μA				0.1		0.1	
					0.1		0.1	
V _{OL}	1a. 24 mA	4.5 V			0.36		0.44	V
	I _{OL} = 24 mA				0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
I _{OZ}	$V_{O} = V_{CC}$ or GND	5.5 V			±0.5		±5	μA
lj	V _I = V _{CC} or GND	5.5 V			±0.1		±1	μA
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			8		80	μA
∆lCC‡	One input at 3.4 V, Other inputs at GND or V _{CC}	5.5 V			0.9		1	mA
C _i	$V_{I} = V_{CC}$ or GND	5 V		4				pF
Co	$V_{O} = V_{CC}$ or GND	5 V		10				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡] This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		T _A = 25°C		MIN MAX		UNIT
		MIN	MAX	WIIIN	IVIAA	UNIT
tw	Pulse duration, LE high	5		5		ns
t _{su}	Setup time, data before LE \downarrow	3.5		3.5		ns
th	Hold time, data LE \downarrow	3.5		3.5		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T _A = 25°C			MIN	МАХ	UNIT
PARAMETER			MIN	TYP	MAX		IVIAA	UNIT
^t PLH	D	Q	1.5	7.5	10.3	1.5	11.8	ns
^t PHL	U		1.5	6.5	9.3	1.5	10	
^t PLH	LE	E Any Q	1.5	8.5	11.3	1.5	13	ns
^t PHL	LL		1.5	8.5	10.9	1.5	12.2	
^t PZH	OE	Any Q	1.5	7	10.7	1.5	12.5	ns
^t PZL	ÛE	Ally Q	1.5	7.5	10.9	1.5	12	115
^t PHZ	OE	Any Q	1.5	10	12.1	1.5	12.2	ns
^t PLZ	ÛE	Ally Q	1.5	7.5	9.5	1.5	10.1	115



SCAS015B - JUNE 1987 - REVISED APRIL 1996

operating characteristics, $V_{CC} = 5 V$, $T_A = 25^{\circ}C$

	PARAMETER			TEST CONDITIONS		
	Bower dissipation consultance per lateb	Outputs enabled	$C_{1} = 50 \text{ pc}$	f = 1 MHz	65	pF
Cpo	Power dissipation capacitance per latch	Outputs disabled	C _L = 50 pF,	t = 1 MHz	54	



- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 3 ns, t_f = 3 ns. D. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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